


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	POWER AND DISCRETES/25/15966	
1.3 Title of PCI	Introduction of Intermediate Label in ACEPACK SMIT Packing Process.	
1.4 Product Category	Pls refer to the impacted products list.	
1.5 Issue date	2025-11-07	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Angelo RAO,Maurizio GIUDICE
2.1.2 Marketing Manager	Paolo PETRALI,Antonino PELLEGRINO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Standard inner labelling	SH1T---ST SHENZHEN -CHINA

4. Description of change

	Old	New
4.1 Description	ACEPACK SMIT Packing Process: 1 Label	ACEPACK SMIT Packing Process: Intermediate Label step introduction.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on final product performance. Impact on processability.	

5. Reason / motivation for change

5.1 Motivation	To prevent any mixing case during packing process.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Q.A. number
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7. Timing / schedule

7.1 Date of qualification results	2025-11-03
7.2 Intended start of delivery	2025-12-08
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

15966 Public product.pdf
15966 Introduction of Intermediate Label in ACEPACK SMIT Packing Process..pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SH32N65DM6AG	
	SH63N65DM6AG	
	SH68N65DM6AG	
	STGSH50M120D	
	STGSH80HB65DAG	

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